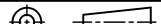
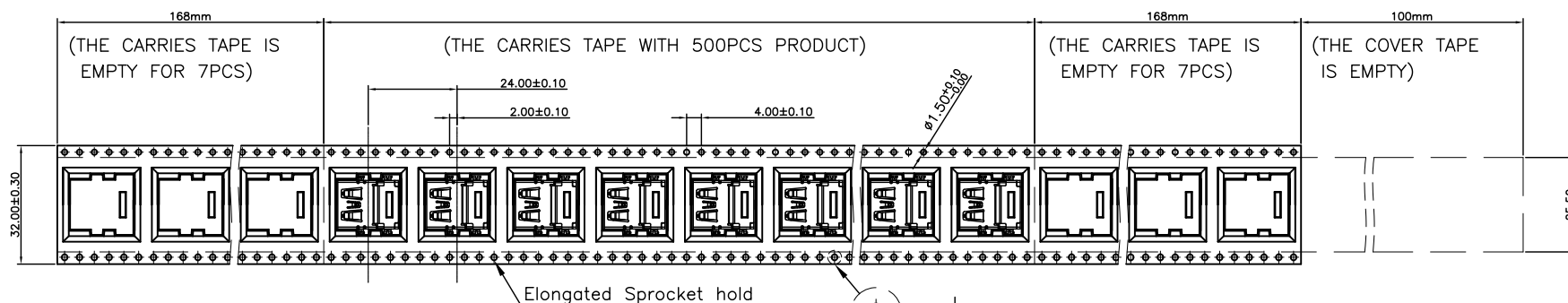
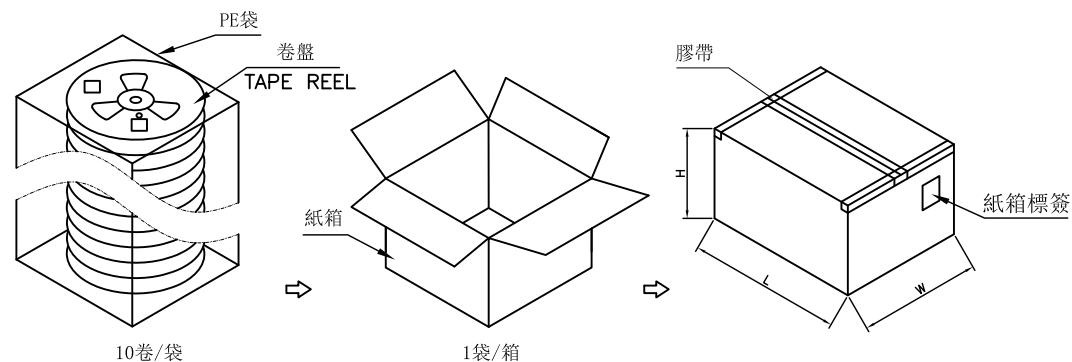
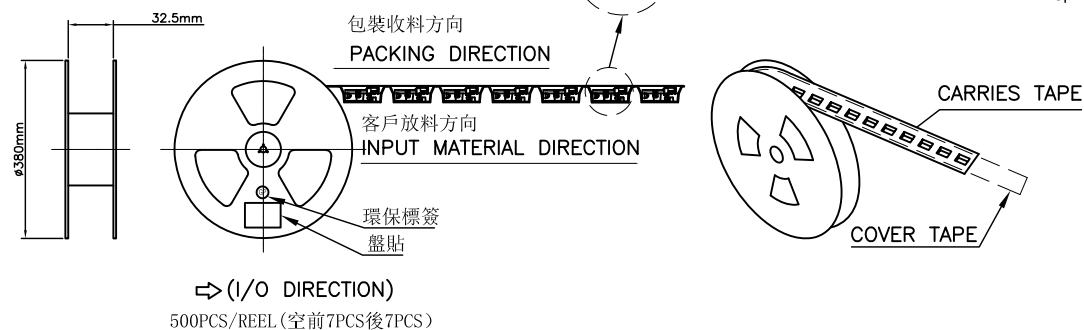


TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.* ±2* X.X* ±0.5*		DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: USB 3.0 AF 沉板反向DIP CH-2.5	
 UNIT: mm [inch]		CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	HYCW172-USBA09-250-XXB
		APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.	
				DRAW NO:	HYC-2511171533
SCALE:1:1	SIZE: A4			SHEET NO.	1 OF 1



SCALE 2:1

0.20±0.05



備注:

1. 防止漏裝，禁止碰歪產品錫腳。
2. 產品在CARRY TPAE中的方向須如圖所示。
3. COVER剝離力：0.1~0.7N。
4. 剝離角度為：165度~180度。
5. 剝離速度為：300mm/miunies。



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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2" X.X' ±0.5' UNIT: mm [inch] SCALE:1:1 SIZE: A4	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 包装图	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	
	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.	
			DRAW NO:	
			SHEET NO.	1 OF 1